



RS6/RS8 Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 30.50%	Copper (Cu)	7440-50-8	2,346.529	99.9761	304,905.6
	Phosphorus (P)	7723-14-0	0.023	0.0010	3.0
	Arsenic (As)	7440-38-2	0.023	0.0010	3.0
	Tin (Sn)	7440-31-5	0.023	0.0010	3.0
	Oxygen (O)	7782-44-7	0.012	0.0005	1.6
	Sulfur (S)	7704-34-9	0.282	0.0120	36.6
	Iron (Fe)	7439-89-6	0.015	0.0006	1.9
	Nickel (Ni)	7440-02-0	0.007	0.0003	0.9
	Bismuth (Bi)	7440-69-9	0.047	0.0020	6.1
	Antimony (Sb)	1309-64-4	0.047	0.0020	6.1
	Lead (Pb)	7439-92-1	0.012	0.0005	1.6
	Zinc (Zn)	7440-66-6	0.070	0.0030	9.1
	Total		2,347.09		
Solder Wafer 0.28%	Lead (Pb)	7439-92-1	19.74	92.50	2,565.0
	Tin (Sn)	7440-31-5	1.07	5.01	139.0
	Silver (Ag)	7440-22-4	0.53	2.48	68.9
		Total		21.34	
Chip 0.19%	Silicon (Si)	7440-21-3	14.00	95.40	1,819.1
	Lead (Pb)	7439-92-1	0.67	4.60	1.3
		Total		14.67	
Molding 68.93%	Epoxy	38891-59-7	5,305.10	100.00	689,339.3
		Total		5,305.10	
Plating 0.10%	Tin (Sn)	7440-31-5	7.72	100.00	1,003.1
		Total		7.72	
	Total mass (mg)		7,695.92		